

## SUA-110E5-30xx-S277

鍍層厚度 :	HOUSING :
Blank : 1u"	Blank : LCP,Blue
2 : 15u"	K : LCP,BLack
3 : 30u"	GR : PBT,Green

### NOTE:

#### 1.MATERIAL:

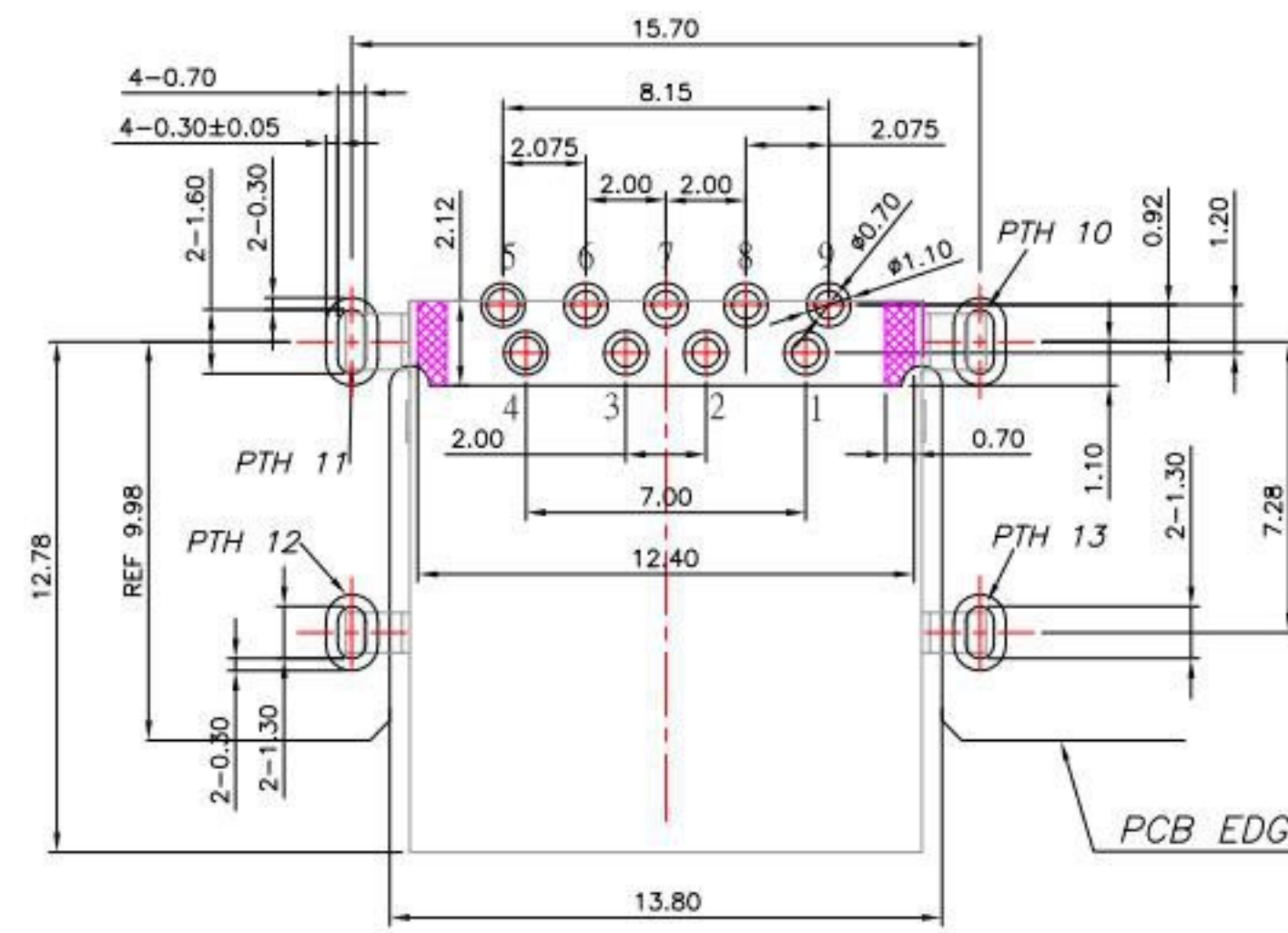
- 1.1 Housing: Plastic,(UL94V-0)
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

#### 2.Finish:

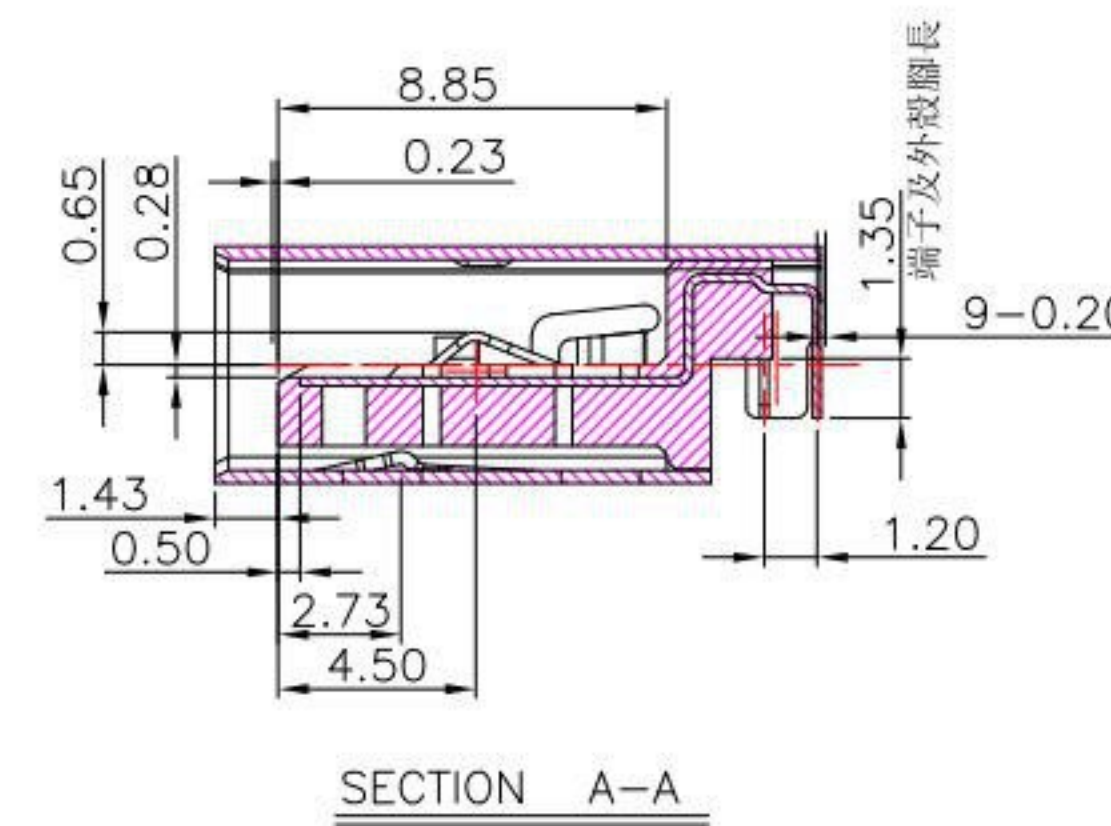
- 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

#### 3.SPECIFICATION:

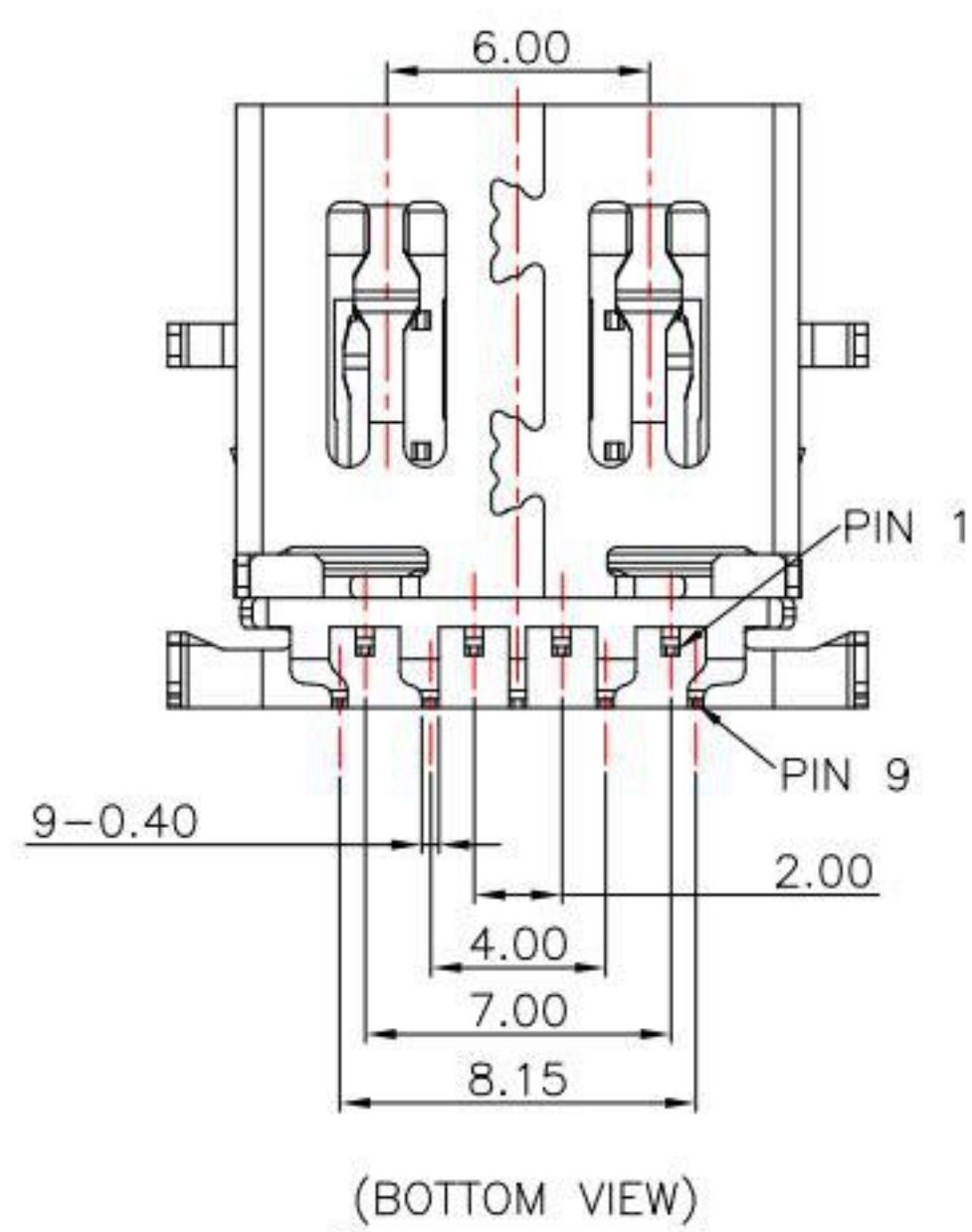
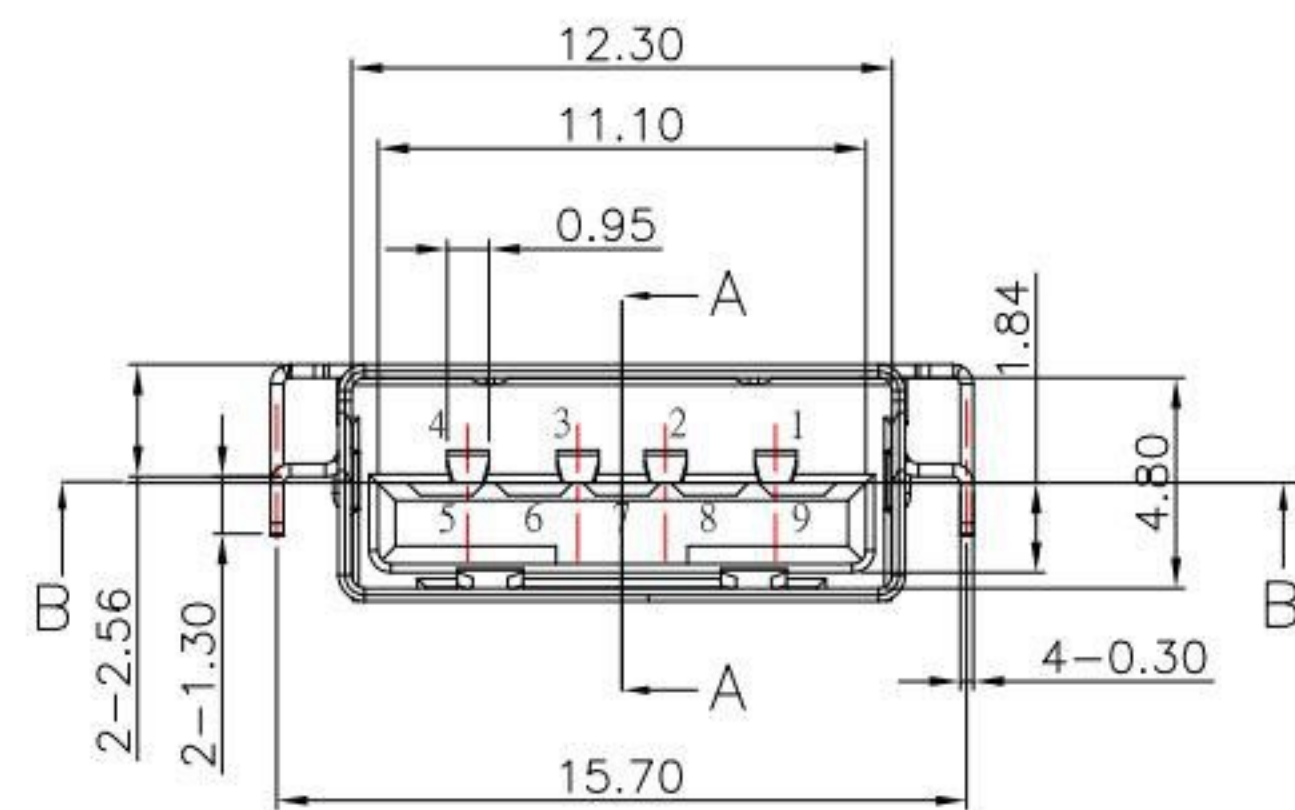
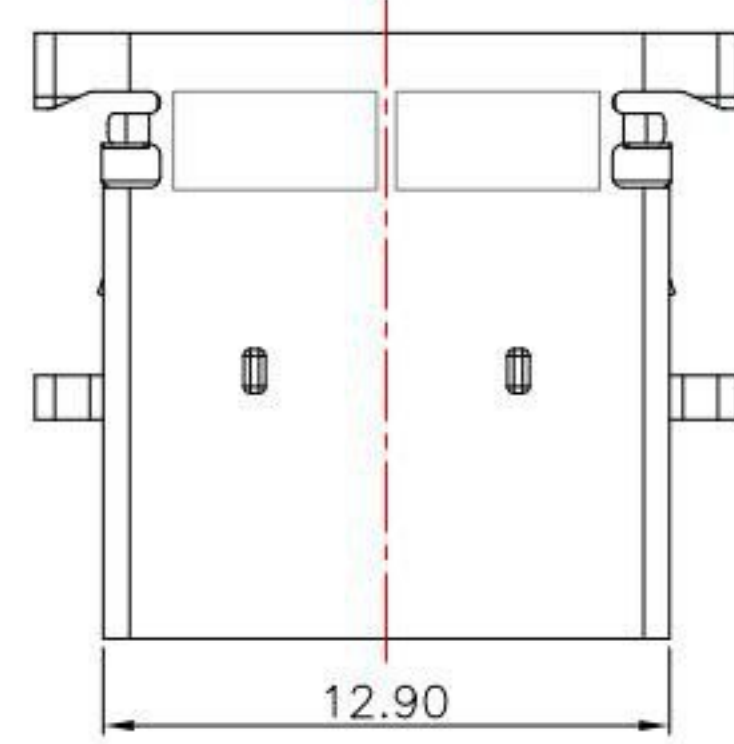
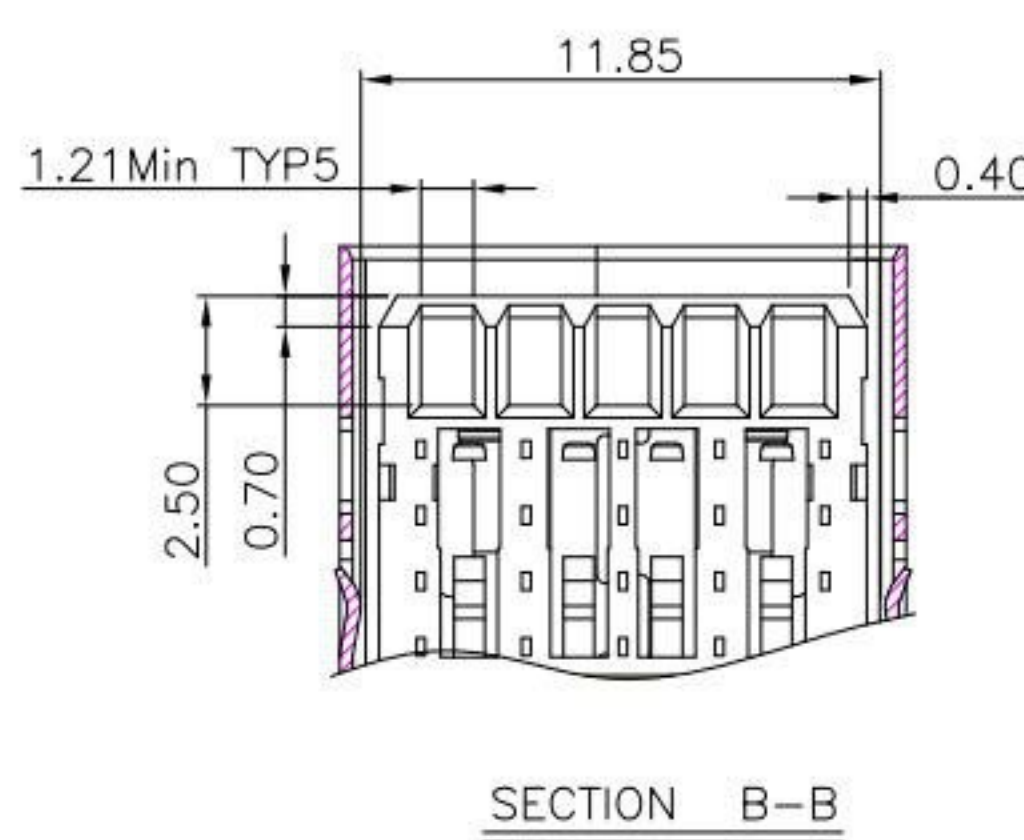
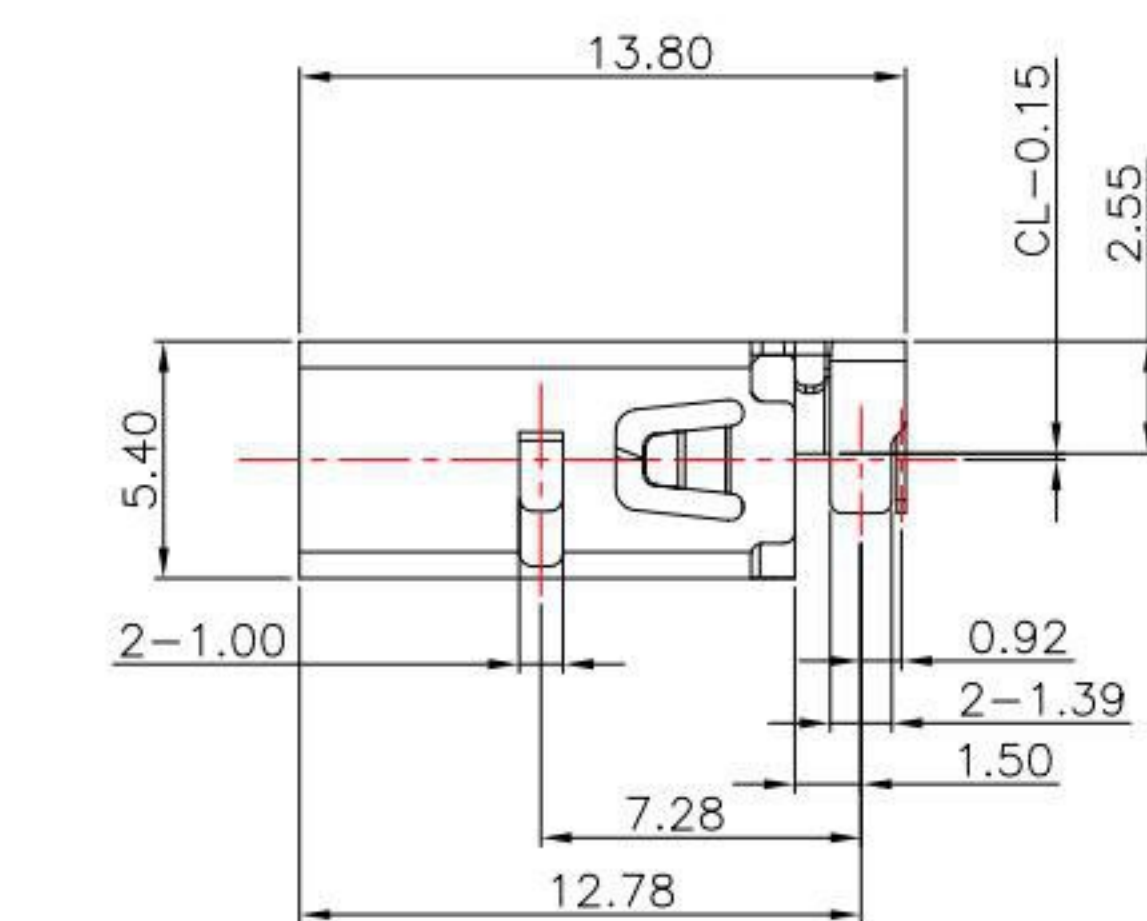
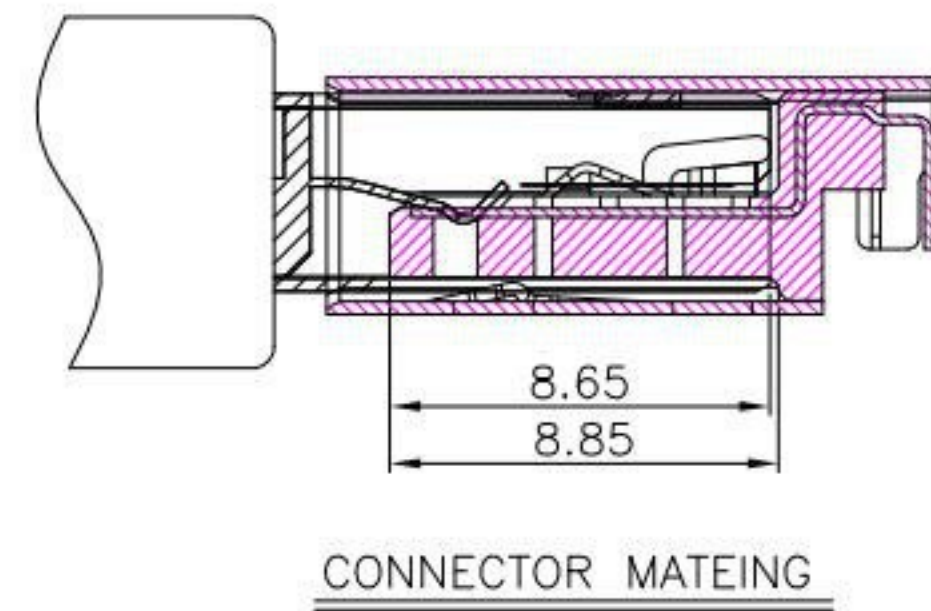
- 3.1 Rate: 30V DC , 1.5 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



### RECOMMENDED PCB LAYOUT



Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST



ITEM NO.	DESCRIPTION	DRAWN	DATE
4	新增尺寸標註	Jack	081920
3	新增PCB LAYOUT尺寸標註	Lan	041819
2	新增顏色及材質選項	Jack	042817
1	更新PCB LAYOUT尺寸	Jack	012017

**KSD** 科斯达电子科技有限公司  
 SWITCH CONNECTOR KSD ELECTRONIC TECHNOLOGY Co., LTD  
 全球 互聯零組件 制造企业

TOLERANCE UNLESS OTHERWISE STATED :  
 Up to 5 ±0.2  
 Above 5 ~ 15 ±0.3  
 Above 15 ~ 30 ±0.4  
 Above 30 ~ 50 ±0.5  
 Angle ±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/19/20		MODLE	USB A/F 3.0 DIP 沉板, 板上H:2.56mm, 無捲邊反向
CHECKED BY:	DATE	FINISH	DWG NO.	SUA-110E5-30xx-S277
Jacky Chen	08/19/20		SHEET NO.	1 of 1
APPROVED BY:	DATE	SCALE	PART NO.	SUA-110E5-30xx-S277
Tony Kao	08/19/20	1 : 1		